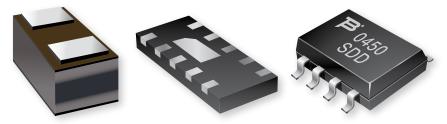


PRODUCT UPDATE MEMO SEMICONDUCTOR COMPONENTS



Select Bourns® Semiconductor Components Change to Country of Origin

Riverside, California — September 24, 2024 - As part of Bourns' standardization of its process for determining the Country Of Origin ("COO") for Bourns® Semiconductor Components assembled in a different country than where the silicon wafer is fabricated or doped, Bourns is updating the COO for the part numbers provided below.

This change is being made based on Bourns' determination that the wafer fabrication process should be given greater weight than the manufacturing process steps that take place in the country of assembly for purposes of determining the applicable COO for Bourns® Semiconductor products.

Accordingly, the COO for Bourns part numbers listed below will change as of November 1, 2024 on all labels and documentation as follows:

Part Number	COO until October 31, 2024	COO as of November 1, 2024
CD0201-T05C	CN	TW
<u>CD0201-T2.0LC</u>	CN	TW
<u>CD0201-T20C</u>	CN	TW
CD0201-T3.3C	CN	TW
CD143A-SR05LC	CN	TW
<u>CD143A-SR2.8</u>	CN	TW
<u>CD143A-SR3.3</u>	CN	TW
CD143A-SR3.3C	CN	TW
<u>CDDFN10-0506N</u>	CN	TW
<u>CDDFN10-0516P</u>	CN	TW
CDDFN10-0524P	CN	TW
<u>CDDFN10-2574N</u>	CN	TW
<u>CDDFN10-3304NA</u>	CN	TW
CDDFN10-3324P	CN	TW

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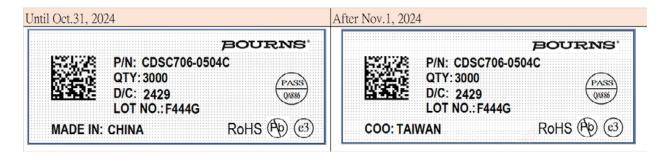


CDDFN10-3324P-13	CN	TW
CDDFN1610-T16S	CN	TW
CDDFN1610-T16S2	CN	TW
CDDFN2-3361P	CN	TW
CDDFN2-T05SC	CN	TW
CDDFN2-T3.3B	CN	TW
CDDFN2-T5.0LC	CN	TW
CDDFN2-T5.5LC	CN	TW
<u>CDDFN6-0504P</u>	CN	TW
<u>CDDFN6-3312P</u>	CN	TW
CDNBS08-SLVU2.8-4	CN	TW
CDNBS08-SLVU2.8-4C	CN	TW
CDSC706-0504C	CN	TW
CDSOD523-T05	CN	TW
<u>CDS0T23-0502B</u>	CN	TW
<u>CDS0T23-0502U</u>	CN	TW
CDS0T236-0502	CN	TW
<u>CDS0T236-0504C</u>	CN	TW
<u>CDS0T236-0504LC</u>	CN	TW

There are no changes to the form, fit, function, quality or reliability of the Bourns® Semiconductor products. There has been no change to the actual place of wafer fabrication nor to the place of final assembly.

This update will only affect the COO printed on new label and shipping paperwork on November 1, 2024 and after, for each of the affected part numbers shown in the table above.

Below, please find an example of how the label will change to clearly show country of origin as "COO Taiwan" and place of final assembly as "Assembled in China."



Bourns will make the COO certificate available on request. Bourns will not make any changes to the labels for the Bourns® Semiconductor products prior to November 1, 2024. For clarification, the COO determined prior to November 1, 2024 based on the country of the assembly shall continue to apply to Bourns part numbers listed in the table above.